



## TO-252 Plastic-Encapsulate MOSFETS

### CC40P04D P-Channel Power MOSFET

| $V_{DS}$ | $R_{DS(ON)}$ (Typ.) | $I_D$ |
|----------|---------------------|-------|
| -40V     | 11m $\Omega$ @-10V  | -40A  |

#### DESCRIPTION

The CC40P04D provides excellent  $R_{DS(ON)}$  with low gate charge.

It can be used in a wide variety of applications.

#### FEATURES

- High density cell design for ultra low  $R_{DS(on)}$
- Excellent package for good heat dissipation
- AEC-Q101 Qualified

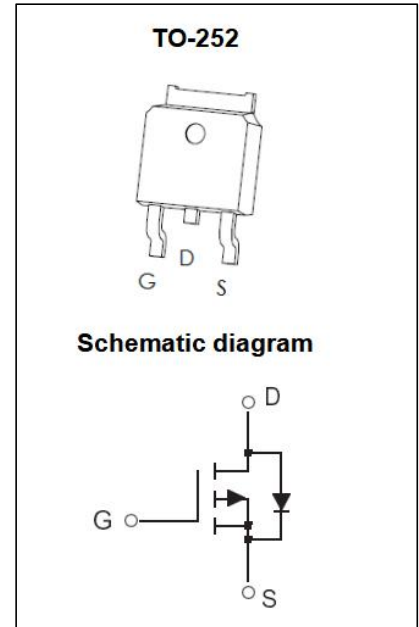
#### APPLICATIONS

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

#### MARKING



U40P04 = Device Code  
XX = Date Code



**ABSOLUTE MAXIMUM RATINGS(T<sub>a</sub>=25°C unless otherwise noted)**

| Parameter                                     | Symbol           | Value     | Unit |
|---|------------------|-----------|------|
| Drain-Source Voltage                          | V <sub>DS</sub>  | -40       | V    |
| Gate-Source Voltage                           | V <sub>GS</sub>  | ±20       | V    |
| Continuous Drain Current                      | I <sub>D</sub>   | -40       | A    |
| Pulsed Drain Current                          | I <sub>DM</sub>  | -160      | A    |
| Single Pulsed Avalanche Energy <sup>(1)</sup> | E <sub>AS</sub>  | 544       | mJ   |
| Power Dissipation                             | P <sub>D</sub>   | 68        | W    |
| Thermal Resistance from Junction to Case      | R <sub>θJC</sub> | 2.2       | °C/W |
| Junction Temperature                          | T <sub>J</sub>   | 175       | °C   |
| Storage Temperature                           | T <sub>STG</sub> | -55~ +175 | °C   |

(1).E<sub>AS</sub> condition: V<sub>DD</sub> = -20V, L = 1mH, R<sub>G</sub> = 25Ω, Starting T<sub>J</sub> = 25°C.

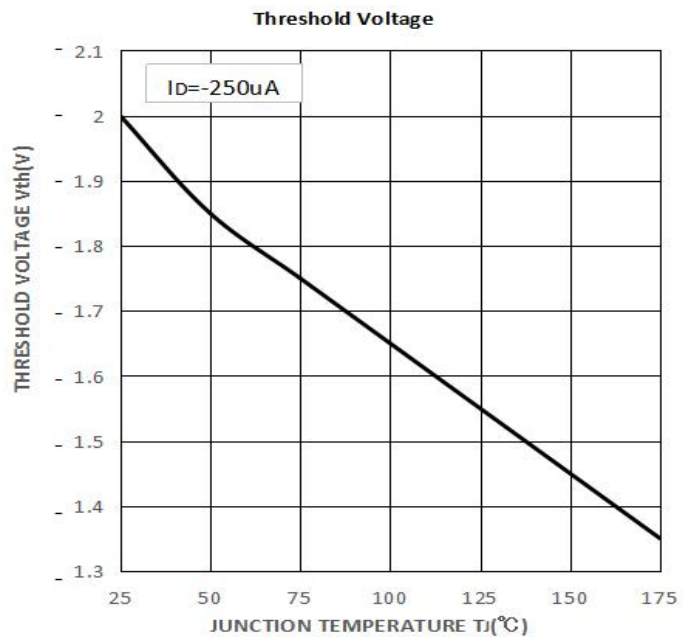
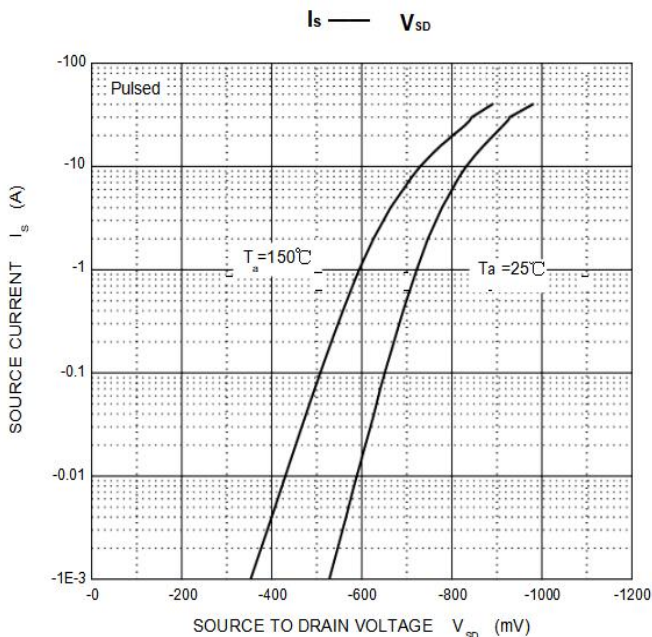
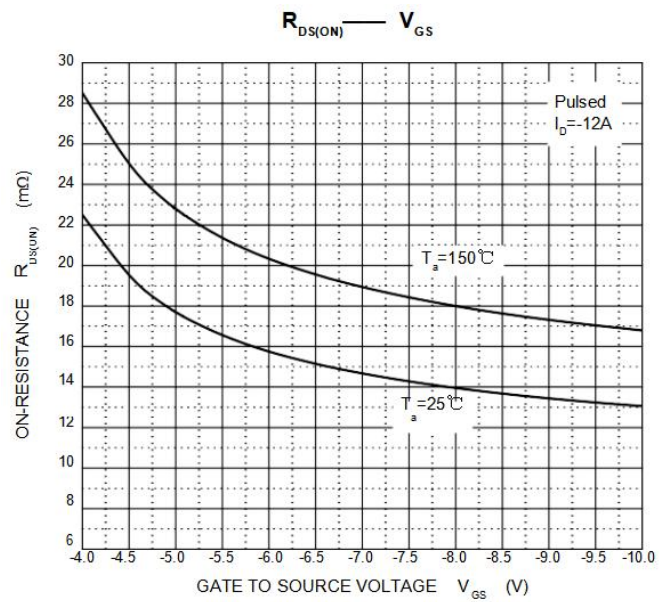
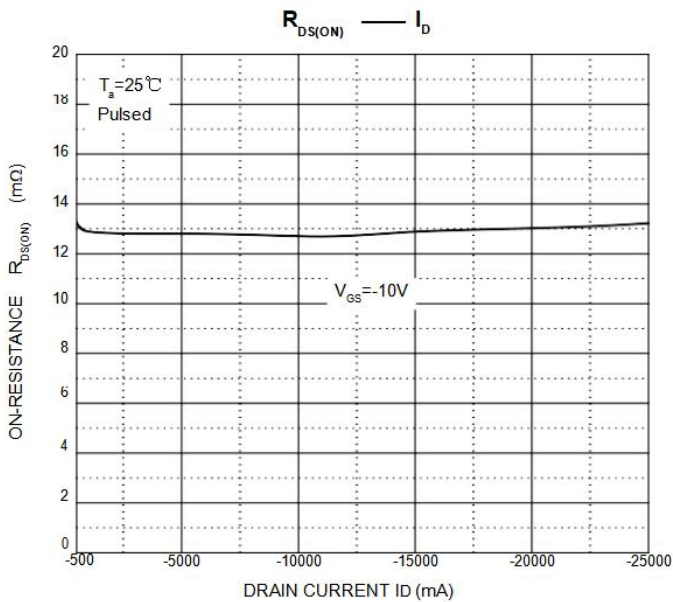
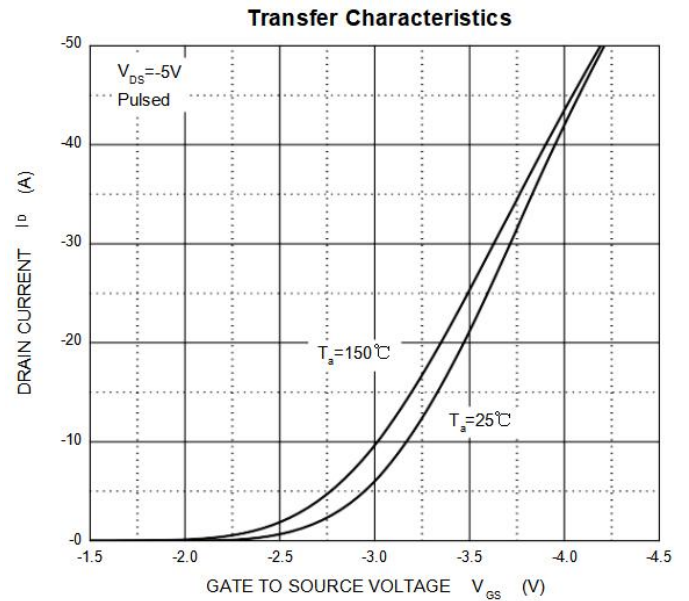
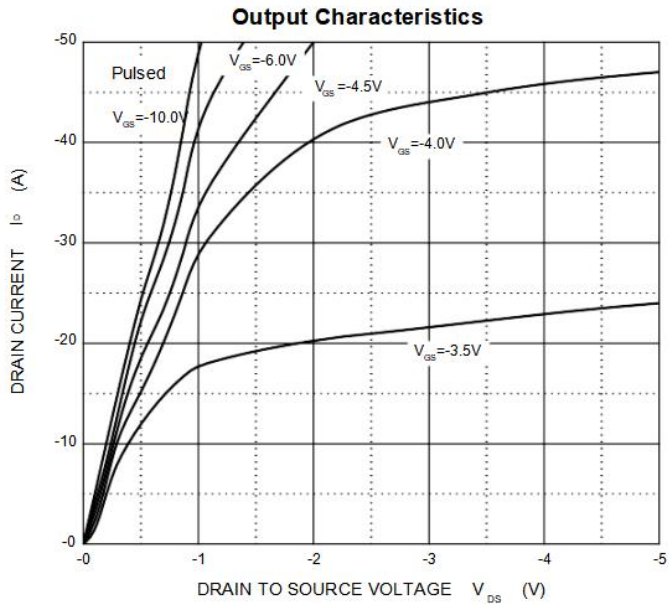
**MOSFET ELECTRICAL CHARACTERISTICS(T<sub>a</sub>=25°C unless otherwise noted)**

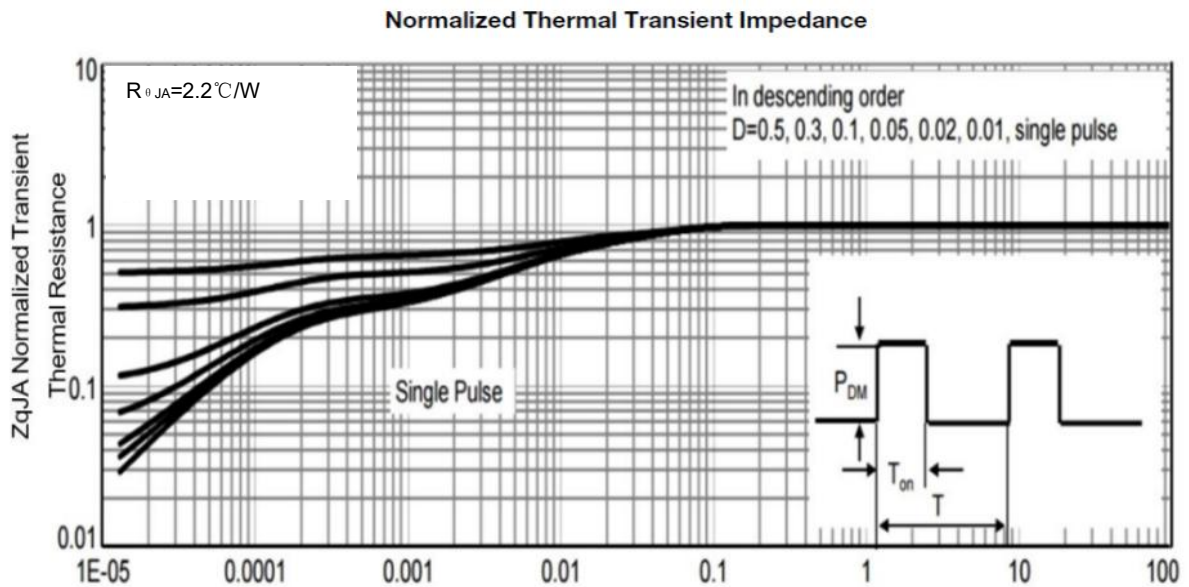
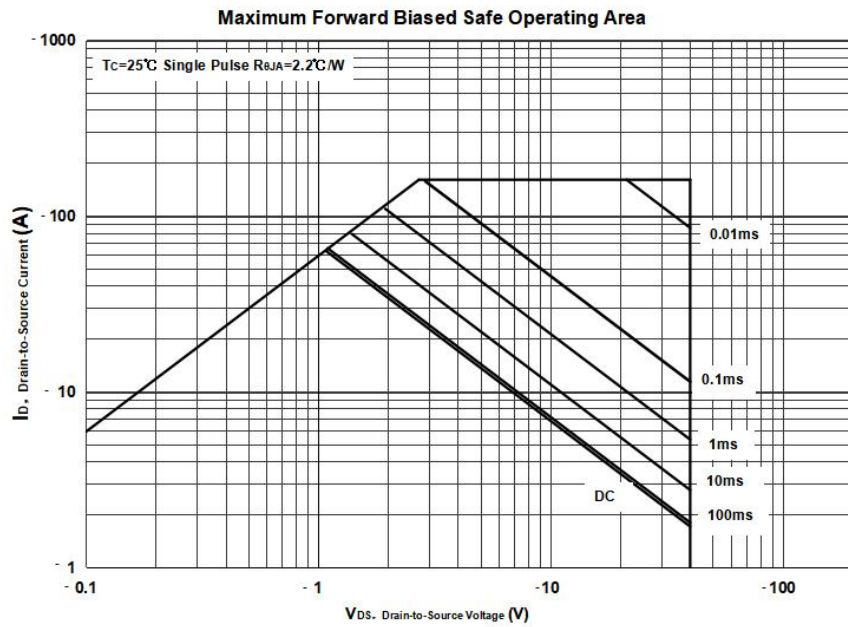
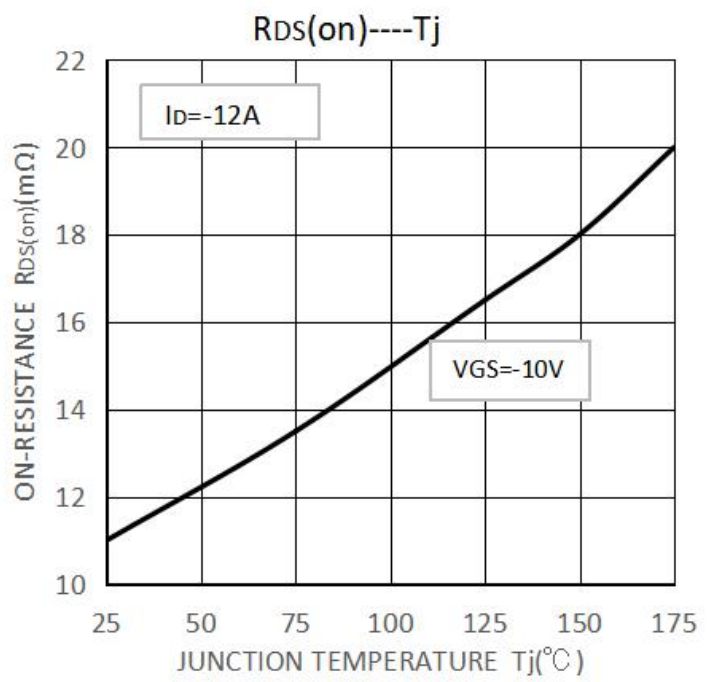
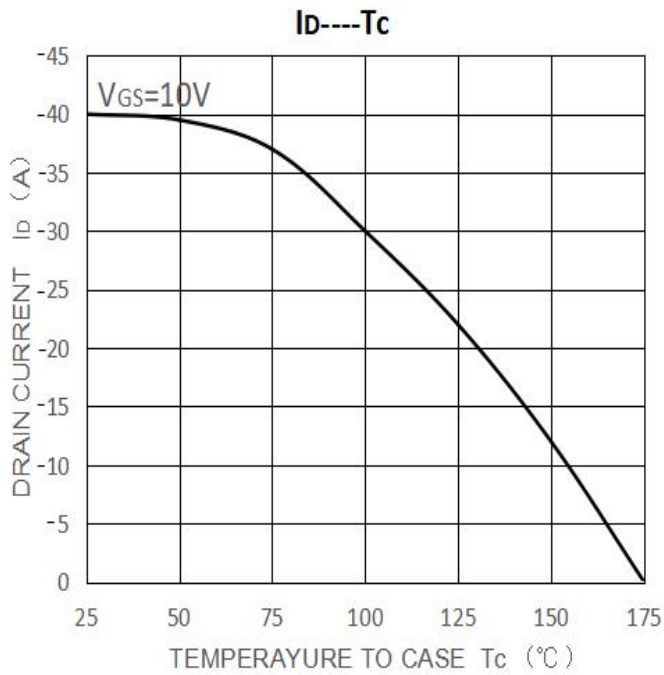
| Parameter                                    | Symbol               | Test Condition  | Min | Type | Max  | Unit |
|--|----------------------|---|-----|------|------|------|
| <b>Off Characteristics</b>                   |                      |   |     |      |      |      |
| Drain-source breakdown voltage               | V <sub>(BR)DSS</sub> | V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA   | -40 |      |      | V    |
| Zero gate voltage drain current              | I <sub>DSS</sub>     | V <sub>DS</sub> = -40V, V <sub>GS</sub> = 0V  |     |      | -1   | μA   |
| Gate-body leakage current                    | I <sub>GSS</sub>     | V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V  |     |      | ±100 | nA   |
| <b>On Characteristics<sup>1</sup></b>        |                      |   |     |      |      |      |
| Gate threshold voltage                       | V <sub>GS(th)</sub>  | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA                                   | -1  | -2   | -3   | V    |
| Drain-source on-resistance                   | R <sub>DS(on)</sub>  | V <sub>GS</sub> = -10V, I <sub>D</sub> = -12A   |     | 11   | 17   | mΩ   |
| Forward transconductance                     | g <sub>FS</sub>      | V <sub>DS</sub> = -5V, I <sub>D</sub> = -12A  | 24  |      |      | S    |
| <b>Dynamic characteristics<sup>2</sup></b>   |                      |   |     |      |      |      |
| Input Capacitance                            | C <sub>iss</sub>     | V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V, f = 1MHz  |     | 4100 |      | pF   |
| Output Capacitance                           | C <sub>oss</sub>     |   |     | 320  |      |      |
| Reverse Transfer Capacitance                 | C <sub>rss</sub>     |   |     | 290  |      |      |
| <b>Switching Characteristics<sup>2</sup></b> |                      |   |     |      |      |      |
| Total Gate Charge                            | Q <sub>g</sub>       | V <sub>DS</sub> = -20V, V <sub>GS</sub> = -10V, I <sub>D</sub> = -12A                         |     | 83   |      | nC   |
| Gate-Source Charge                           | Q <sub>gs</sub>      |   |     | 18   |      |      |
| Gate-Drain Charge                            | Q <sub>gd</sub>      |   |     | 14   |      |      |
| Turn-on delay time                           | t <sub>d(on)</sub>   | V <sub>DD</sub> = -20V, I <sub>D</sub> = -20A<br>V <sub>GS</sub> = -10V, R <sub>G</sub> = 3Ω, |     | 11   |      | ns   |
| Turn-on rise time                            | t <sub>r</sub>       |   |     | 19   |      |      |
| Turn-off delay time                          | t <sub>d(off)</sub>  |   |     | 40   |      |      |
| Turn-off fall time                           | t <sub>f</sub>       |   |     | 26   |      |      |
| <b>Diode Characteristics</b>                 |                      |   |     |      |      |      |
| Diode Forward Voltage                        | V <sub>SD</sub>      | V <sub>GS</sub> = 0V, I <sub>S</sub> = -10A   |     |      | -1.2 | V    |

**Note :**

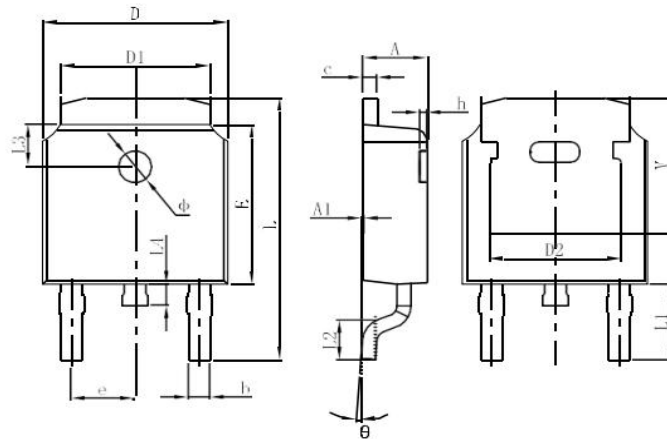
1. Pulse Test : Pulse Width ≤ 300μs, duty cycle ≤ 2%.
2. Guaranteed by design, not subject to production.

# Characteristics Curve:



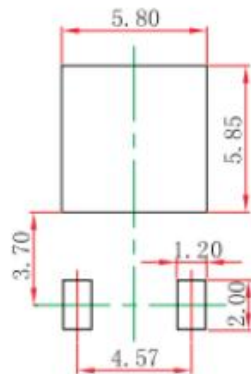


## TO-252 Package Outline Dimensions



| Symbol | Dimensions In Millimeters |        | Dimensions In Inches |       |
|--------|---------------------------|--------|----------------------|-------|
|        | Min.                      | Max.   | Min.                 | Max.  |
| A      | 2.200                     | 2.400  | 0.087                | 0.094 |
| A1     | 0.000                     | 0.127  | 0.000                | 0.005 |
| b      | 0.635                     | 0.770  | 0.025                | 0.030 |
| c      | 0.460                     | 0.580  | 0.018                | 0.023 |
| D      | 6.500                     | 6.700  | 0.256                | 0.264 |
| D1     | 5.100                     | 5.460  | 0.201                | 0.215 |
| D2     | 4.830 REF.                |        | 0.190 REF.           |       |
| E      | 6.000                     | 6.200  | 0.236                | 0.244 |
| e      | 2.186                     | 2.386  | 0.086                | 0.094 |
| L      | 9.712                     | 10.312 | 0.382                | 0.406 |
| L1     | 2.900 REF.                |        | 0.114 REF.           |       |
| L2     | 1.400                     | 1.700  | 0.055                | 0.067 |
| L3     | 1.600 REF.                |        | 0.063 REF.           |       |
| L4     | 0.600                     | 1.000  | 0.024                | 0.039 |
| φ      | 1.100                     | 1.300  | 0.043                | 0.051 |
| θ      | 0°                        | 8°     | 0°                   | 8°    |
| h      | 0.000                     | 0.300  | 0.000                | 0.012 |
| V      | 5.250 REF.                |        | 0.207 REF.           |       |

## TO-252 Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: 0.5mm.
3. The pad layout is for reference purposes only.

### NOTICE

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| Date of change | Rev # | revise content |
|----------------|-------|----------------|
| 2023/03/07     | A/0   | /              |
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